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## NEWS RELEASE

### ISI Increases Reballing Capacity And Implements 100% Optical Inspection

(Camarillo, CA) - Interconnect Systems, Inc. (ISI). In response to the increasing demand for reballing, ISI has made substantial investments in process and capacity upgrades including automated 100% optical inspection. ISI's process of removing lead-free (RoHS) solder spheres then attaching leaded Sn63Pb37 eutectic spheres, has been qualified by leading Commercial, Industrial, Military and Aerospace companies.

Most Semiconductor suppliers have converted to lead free packaging creating compatibility and reliability dilemmas for Military, Aerospace and Hi-Rel applications. The ISI reballing process is a reliable and affordable solution. ISI tailors dimensional specifications and processes to each part. Specific control parameters for each phase of handling, production and controls for temperature, humidity, ESD protection, ball size/position tolerance specifications, automation, cleanliness, 100% optical inspection and repackaging are rigorously maintained.

For more information visit [www.isipkg.com](http://www.isipkg.com).

